

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



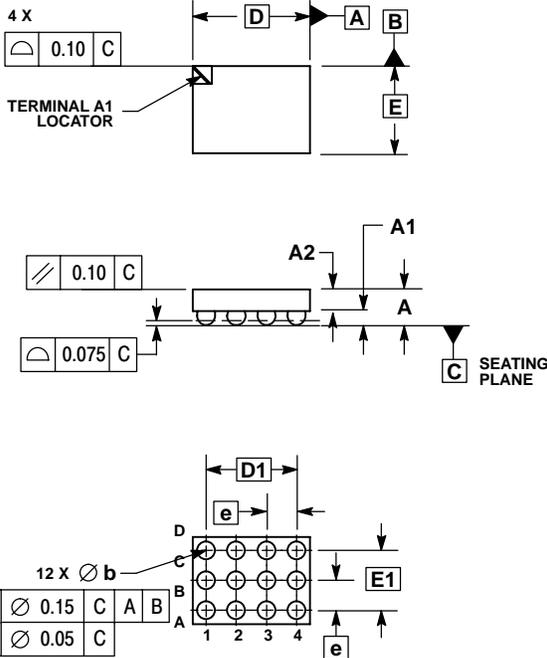
12 PIN FLIP-CHIP CSP

CASE 499AB-01
ISSUE A

DATE 18 OCT 2004



SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.550	0.650
A1	0.215	0.265
A2	0.36 REF	
D	1.90	2.00
E	1.4	1.5
b	0.250	0.350
e	0.500 BSC	
D1	1.500 BSC	
E1	1.000 BSC	

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	12 PIN FLIP-CHIP CSP	PAGE 1 OF 2

